

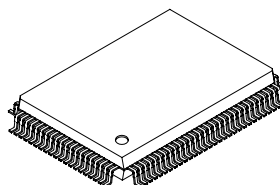
CMOS 8-bit Single Chip Microcomputer

Description

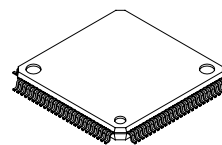
The CXP87452/87460 is a CMOS 8-bit micro-computer which consists of A/D converter, serial interface (2ch independently), timer/counter, time base timer, vector interruption, high precision timing pattern generation circuit (PPG 2ch independently, RTG 2ch independently), PWM generator, general purpose prescaler, PWM for tuner, VCR vertical sync separation circuit and the measuring circuit which measure signals of capstan FG and drum FG/PG and other servo systems, as well as basic configurations like 8-bit CPU, ROM, RAM and I/O port. They are integrated into a single chip.

Also CXP87452/87460 provides power on reset function, sleep/stop function which enables to lower power consumption .

100 pin QFP (Plastic)



100 pin LQFP (Plastic)



Structure

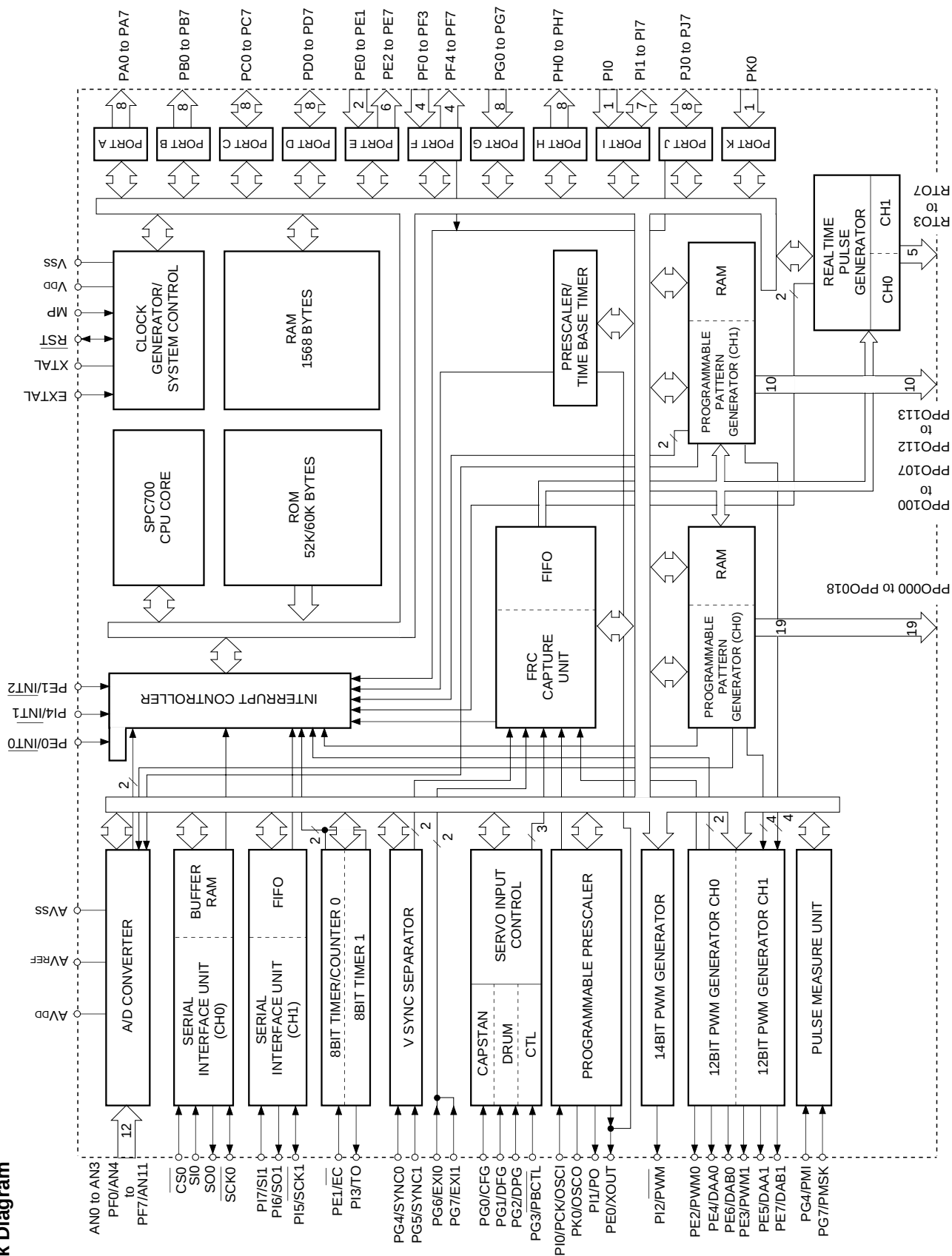
Silicon gate CMOS IC

Features

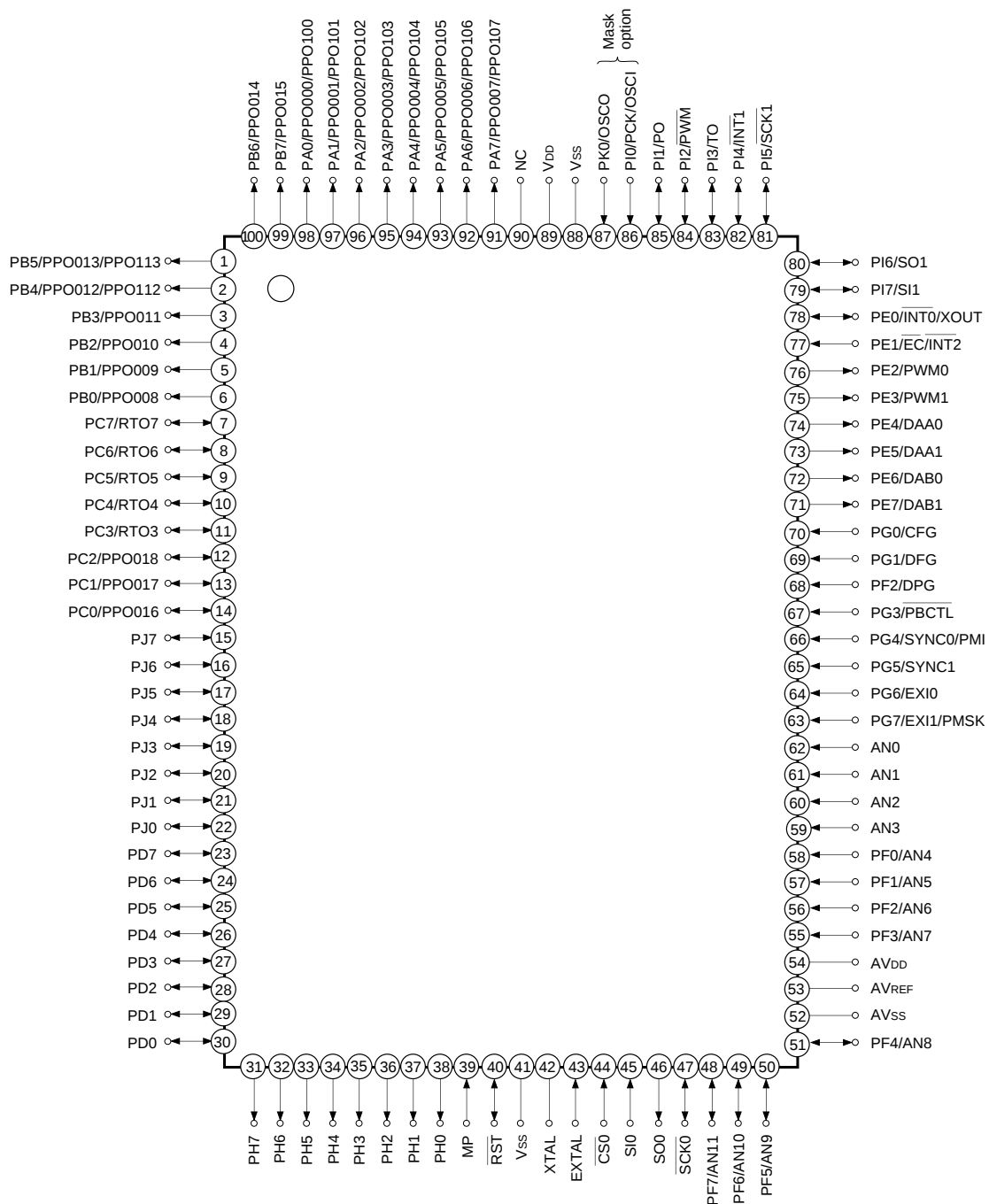
- A wide instruction set (213 instructions) which cover various types of data
 - 16-bit arithmetic instruction/multiplication and division instructions/boolean bit operation instruction
- Minimum instruction cycle
 - During operation 333ns/12MHz (3.0 to 5.5V)
 - During operation 250ns/16MHz (4.5 to 5.5V)
- Incorporated ROM capacity
 - 52K bytes (CXP87452)
 - 60K bytes (CXP87460)
- Incorporated RAM capacity
 - 1568 bytes
- Peripheral functions
 - A/D converter
 - 8-bit, 12-channel, successive approximation system (Conversion time: 20μs/16MHz)
 - Serial interface
 - Incorporated buffer RAM (1 to 32 bytes auto transfer) 1-channel
 - Incorporated 8-bit and 8-stage FIFO (1 to 8 bytes auto transfer) 1-channel
 - 8-bit timer, 8-bit timer/counter, 19-bit time base timer
 - Timer
 - PPG 19 pins 32-stage programmable
 - PPG 10 pins 21-stage programmable
 - RTG 5 pins 2-channel
 - High precision timing pattern generator
 - PWM 12-bit, 2-channel (Repetitive frequency 62.5kHz/16MHz)
 - DA gate pulse 12-bit, 4-channel
 - Capstan FG, Drum FG/PG, CTL input
 - PWM/DA gate output
 - Incorporated 26-bit and 8-stage FIFO
 - 14-bit, 1-channel
 - 10-bit (System clock asynchronous)
 - Servo input control
 - 18 factors, 14 vectors, multi-interruption possible
 - VSYNC separator
 - SLEEP/STOP
 - FRC capture unit
 - 100-pin plastic QFP/LQFP
 - PWM output
 - CXP87400 100-pin ceramic QFP/LQFP
 - General purpose prescaler
 - Pulse cycle measurement circuit
- Interruption
 - 18 factors, 14 vectors, multi-interruption possible
- Standby mode
 - SLEEP/STOP
- Package
 - 100-pin plastic QFP/LQFP
- Piggyback/evaluation chip
 - CXP87400 100-pin ceramic QFP/LQFP

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Block Diagram

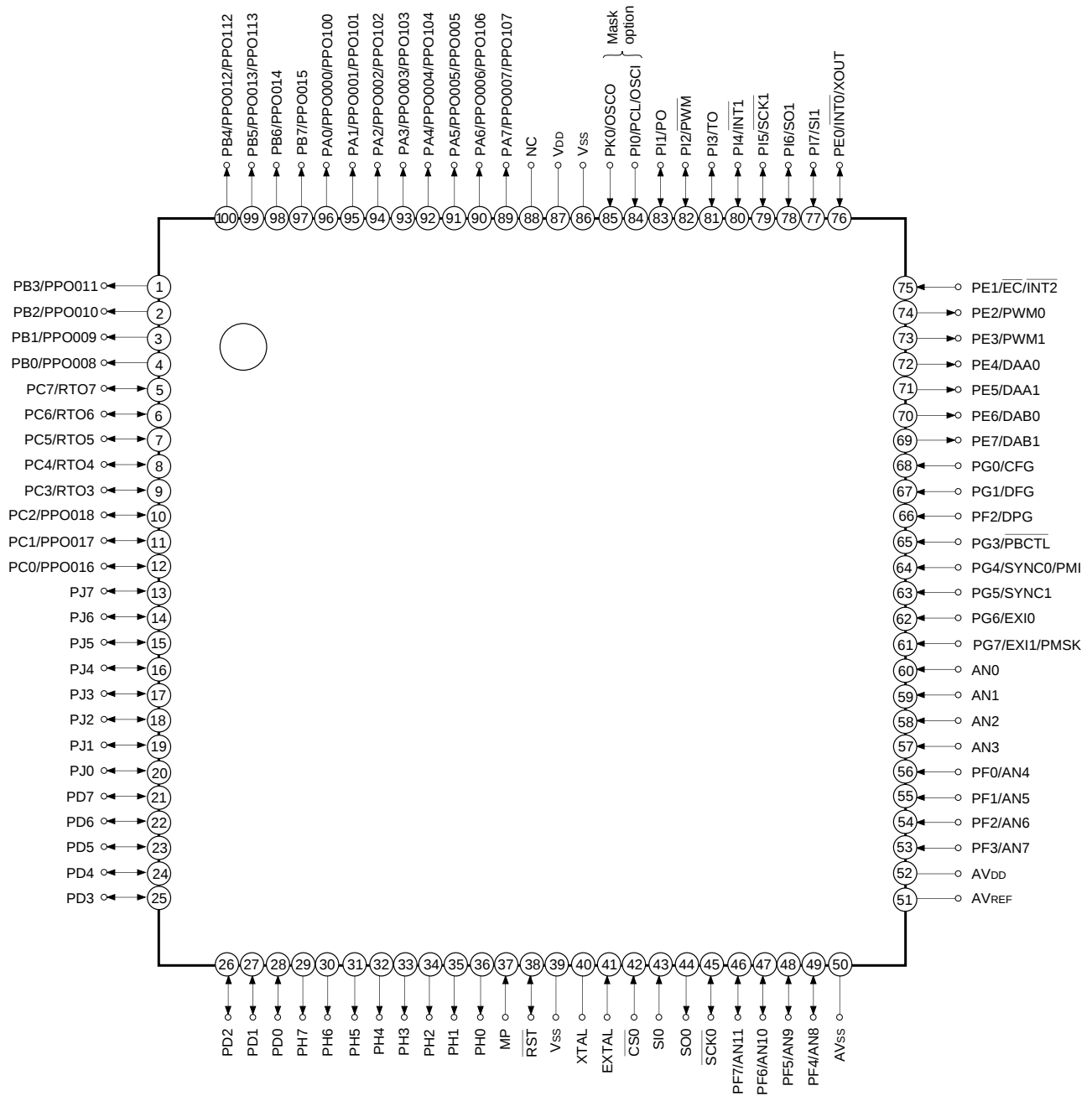


Pin Configuration 1 (Top View) 100 pin QFP Package



- Note)**
1. NC (Pin 90) is always connected to V_{DD}.
 2. Vss (Pins 41 and 88) are both connected to GND.

Pin Configuration 2 (Top View) 100 pin LQFP Package



- Note)**
1. NC (Pin 88) is always connected to VDD.
 2. Vss (Pins 39 and 86) are both connected to GND.

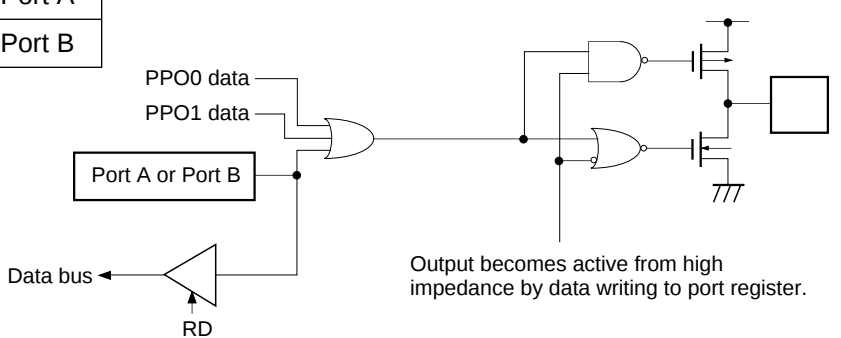
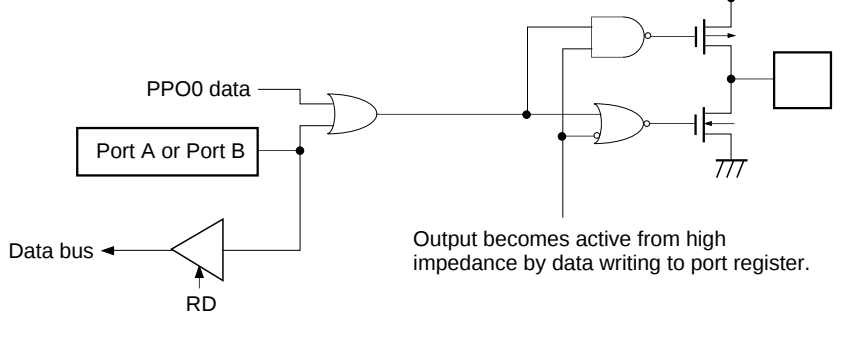
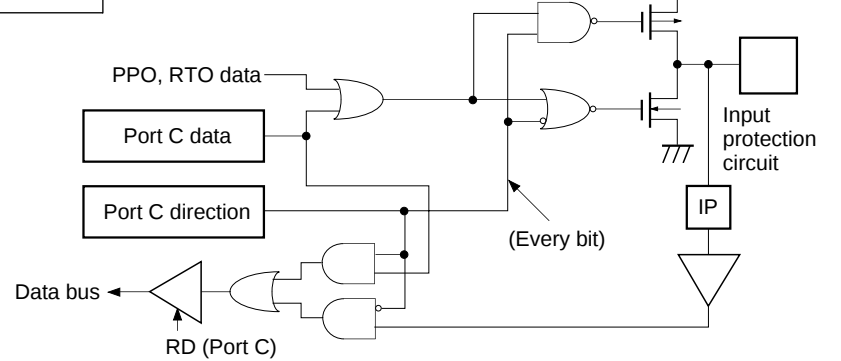
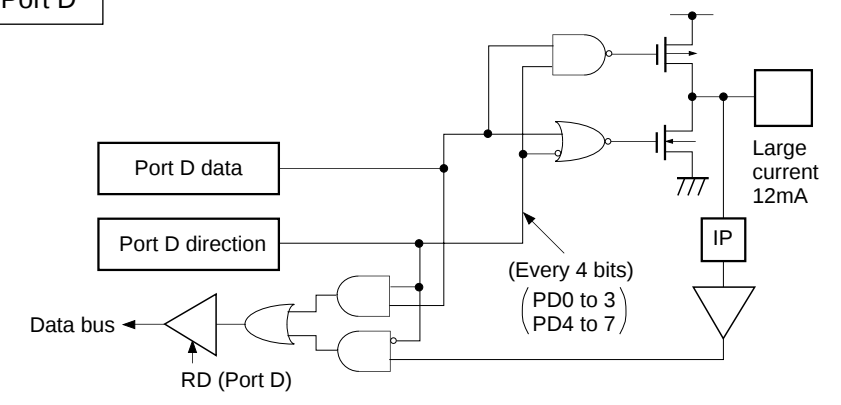
Pin Description

Symbol	I/O	Description			
PA0/PPO000 /PPO100 to PA7/PPO007 /PPO107	Output/ Real time output	(Port A) 8-bit output port. Data is gated with PPO0 and PPO1 contents by OR-gate and they are output. (8 pins)	Programmable pattern generator (PPG0, PPG1) output. Functions as high precision real time pulse output port. (PPG0 19 pins PPG1 10 pins)		
PB0/PPO008 to PB7/PPO015	Output/ Real time output	(Port B) 8-bit output port. Data is gated with PPO0 and PPO1 contents by OR-gate and they are output. (8 pins)			
PC0/PPO016 to PC2/PPO018	I/O/ Real time output	(Port C) 8-bit I/O port. Enables to specify I/O by bit unit. Data is gated with PPO or RTO contents by OR-gate and they are output. (8 pins)			
PC3/RTO3 to PC7/RTO7	I/O/ Real time output		Real time pulse generator (RTG) output. Functions as high precision real time pulse output port. (5 pins)		
PD0 to PD7	I/O	(Port D) 8-bit I/O port. Enable to specify I/O by 4-bit unit. Enables to drive 12mA sinc current. (During 5V ± 0.5V operation) (8 pins)			
PE0/ $\overline{\text{INT0}}$ /XOUT	Input/input/output	(Port E) 8-bit port. Lower 2 bits are input port and upper 6 bits are output port. (8 pins)	Input pin to request external interruption. Active when falling edge.		1/2 dividing clock output of XTAL or OSCO.
PE1/ $\overline{\text{EC}}$ / $\overline{\text{INT2}}$	Input/input/input		External event input pin for timer/counter.	Input pin to request external interruption. Active when falling edge.	
PE2/PWM0	Output/output		PWM output pins. (2 pins)		
PE3/PWM1	Output/output				
PE4/DAA0	Output/output				
PE5/DAA1	Output/output				
PE6/DAB0	Output/output		DA gate pulse output pins. (4 pins)		
PE7/DAB1	Output/output				
AN0 to AN3	Input	Analog input pins to A/D converter. (12 pins)			
PF0/AN4 to PF3/AN7	Input/input	(Port F) Lower 4 bits are input port and upper 4 bits are output port. Lower 4 bits also serve as standby release input pin. (8 pins)			
PF4/AN8 to PF7/AN11	Output/input				
$\overline{\text{SCK0}}$	I/O	Serial clock (CH0) I/O pin.			
SO0	Ouput	Serial data (CH0) output pin.			
SI0	Input	Serial data (CH0) input pin.			
$\overline{\text{CS0}}$	Input	Serial chip select (CH0) input pin.			

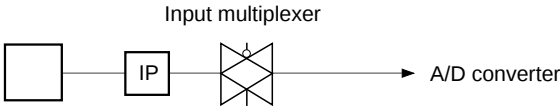
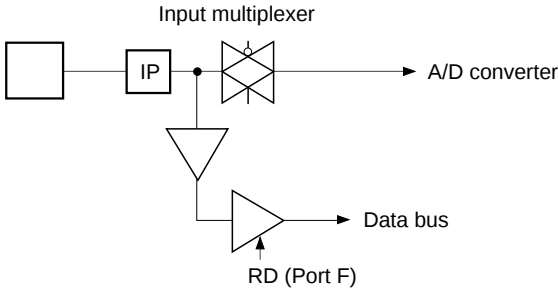
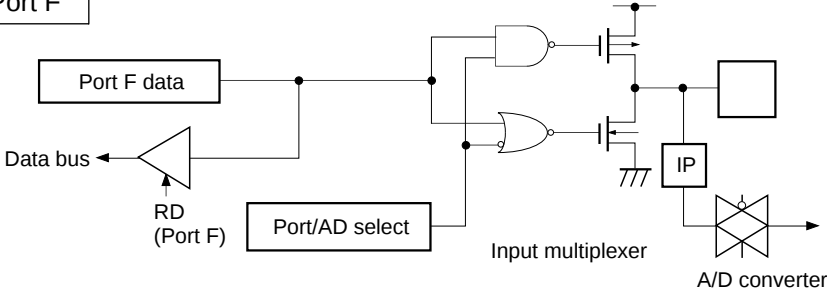
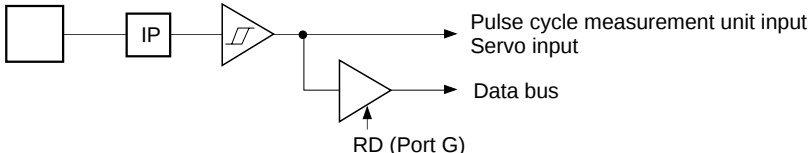
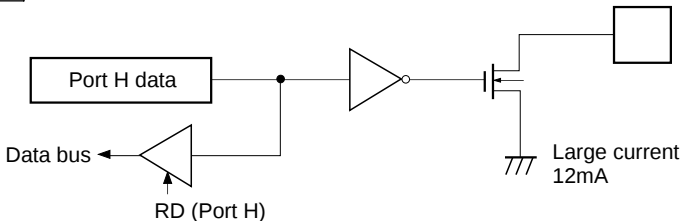
Symbol	I/O	Description			
PG0/CFG	Input/input	(Port G) 8-bit input port. (8 pins)	Capstan FG input pin.		
PG1/DFG	Input/input		Drum FG input pin.		
PG2/DPG	Input/input		Drum PG input pin.		
PG3/ $\overline{\text{PBCTL}}$	Input/input		Playback CTL pulse input pin.		
PG4/SYNC0 /PMI	Input/input/input		Composite sync signal input pin.	Measuring pulse signal input pin of pulse cycle measuring unit.	
PG5/SYNC1	Input/input				
PG6/EXI0	Input/input		External input pin to FRC capture unit.		
PG7/EXI1/ PMSK	Input/input/input			Measuring enable signal input pin of pulse cycle measuring unit.	
PH0 to PH7	Output	(Port H) 8-bit output port; large current, N-ch open drain output. (8 pins)			
PI0/PCK /OSCI	Input/input/input	(Port I) Lower 1 bit is input port (mask option) and upper 7 bits are I/O port. I/O port can be specified by bit unit. (8 pins)	External clock input pin of general purpose prescaler.	Connecting pin of crystal oscillation circuit for general purpose prescaler. (Mask option)	
PI1/PO	I/O/output		General purpose prescaler output pin.		
PI2/ $\overline{\text{PWM}}$	I/O/output		14-bit PWM output pin.		
PI3/TO	I/O/output		Timer/counter, output pin. (duty = 50%)		
PI4/ $\overline{\text{INT1}}$	I/O/input		Input pin to request external interruption. Active when falling edge.		
PI5/ $\overline{\text{SCK1}}$	I/O/I/O		Serial clock (CH1) I/O pin.		
PI6/SO1	I/O/output		Serial data (CH1) output pin.		
PI7/SI1	I/O/input		Serial data (CH1) input pin.		
PJ0 to PJ7	I/O	(Port J) 8-bit I/O port. Function as standby release input can be specified by bit unit. I/O can be specified by bit unit.			

Symbol	I/O	Description	
PK0/OSCO	Input/output	Input port. (Mask option)	Connecting pin of crystal oscillation circuit for general purpose prescaler. (Mask option)
EXTAL	Input	Connecting pin of crystal oscillator for system clock. When supplying the external clock, input the external clock to EXTAL pin and input opposite phase clock to XTAL pin.	
XTAL	Output		
$\overline{\text{RST}}$	I/O	System reset pin of active "L" level. $\overline{\text{RST}}$ pin is I/O pin, which output "L" level by incorporated power on reset function when power on. (Mask option)	
MP	Input	Microprocessor mode input pin. Always connect to GND.	
AV _{DD}		Positive power supply pin of A/D converter.	
AV _{REF}	Input	Reference voltage input pin of A/D converter.	
AV _{SS}		GND pin of A/D converter.	
V _{DD}		Positive power supply pin.	
V _{SS}		GND pin. Connect both V _{SS} pins to GND.	

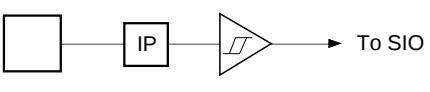
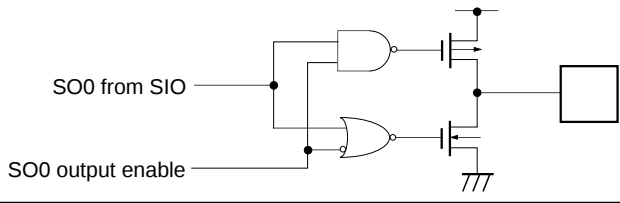
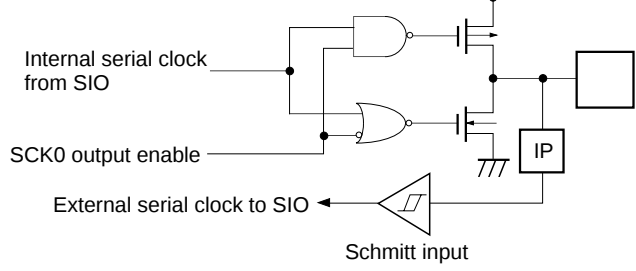
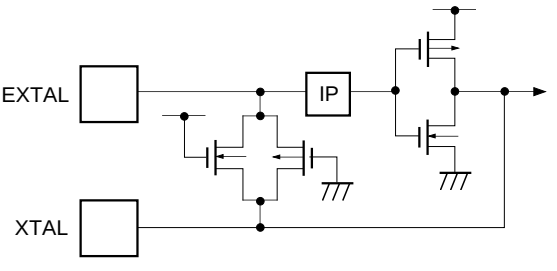
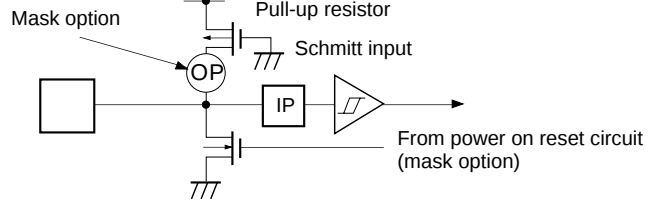
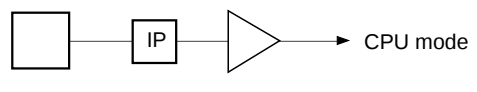
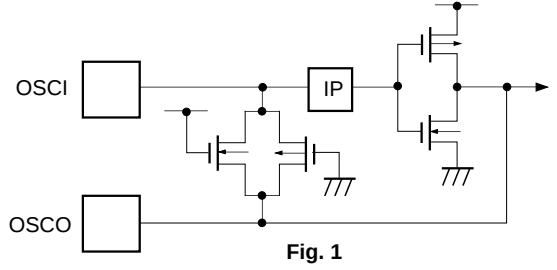
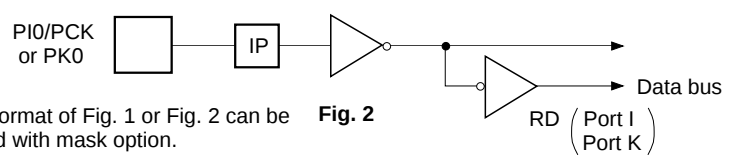
Input/Output Circuit Format for Pins

Pin	Circuit format	When reset
PA0/PPO000 /PPO100 to PA7/PPO007 /PPO107 PB4/PPO012 /PPO112 to PB5/PPO013 /PPO113 10 pins	Port A Port B  Output becomes active from high impedance by data writing to port register.	Hi-Z
PB0/PPO008 to PB3/PPO011 PB6/PPO014 to PB7/PPO015 6 pins	Port B  Output becomes active from high impedance by data writing to port register.	Hi-Z
PC0/PPO016 to PC2/PPO018 PC3/RTO3 to PC7/RTO7 8 pins	Port C  (Every bit) Input protection circuit IP	Hi-Z
PD0 to PD7 8 pins	Port D  (Every 4 bits) (PD0 to 3) (PD4 to 7) Large current 12mA IP	Hi-Z

Pin	Circuit format	When reset
PE1/ $\overline{\text{EC}}$ / $\overline{\text{INT2}}$ 1 pin	Port E	Hi-Z
PE0/ $\overline{\text{INT0}}$ / $\overline{\text{XOUT}}$ 1 pin	Port E	Hi-Z
PE2/PWM0 PE3/PWM1 PE4/DAA0 PE5/DAA1 4 pins	Port E	Hi-Z
PE6/DAB0 PE7/DAB1 2 pins	Port E	H level

Pin	Circuit format	When reset
AN0 to AN3 4 pins		Hi-Z
PF0/AN4 to PF3/AN7 4 pins	Port F 	Hi-Z
PF4/AN8 to PF7/AN11 4 pins	Port F 	Hi-Z
PG0/CFG PG1/DFG PG2/DPG PG3/PBCTL PG4/SYNC0/PMI PG5/SYNC1 PG6/EXI0 PG7/EXI1/PMSK 8 pins	Port G  Note) For PG4/SYNC0, PG5/SYNC1, CMOS schmitt input and TTL schmitt input can be selected with the mask option.	Hi-Z
PH0 to PH7 8 pins	Port H 	Hi-Z

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Pin	Circuit format		When reset
$\overline{\text{CS0}}$ SIO 2 pins	Schmitt input 		Hi-Z
SO0 1 pin			Hi-Z
$\overline{\text{SCK0}}$ 1 pin			Hi-Z
EXTAL XTAL 2 pins	 • Shows the circuit composition during oscillation. • Feedback resistor is removed during stop.		Oscillation
$\overline{\text{RST}}$ 1 pin			L level
MP 1 pin			Hi-Z
PI0/PCK/OSCI PK0/OSCO 2 pins	Port I	 Fig. 1  Fig. 2 Note) Circuit format of Fig. 1 or Fig. 2 can be selected with mask option.	Oscillation
	Port K		

Absolute Maximum Ratings

(V_{SS} = 0V)

Item	Symbol	Rating	Unit	Remarks
Power supply voltage	V _{DD}	−0.3 to +7.0	V	
	AV _{DD}	AV _{SS} to +7.0* ¹	V	
	AV _{SS}	−0.3 to +0.3	V	
Input voltage	V _{IN}	−0.3 to +7.0* ²	V	
Output voltage	V _{OUT}	−0.3 to +7.0* ²	V	
High level output current	I _{OH}	−5	mA	
High level total output current	ΣI _{OH}	−50	mA	Total of output pins
Low level output current	I _{OL}	15	mA	Other than large current output pins: per pin
	I _{OLC}	20	mA	Large current output pin* ³ : per pin
Low level total output current	ΣI _{OL}	130	mA	Total of output pins
Operating temperature	T _{opr}	−20 to +75	°C	
Storage temperature	T _{stg}	−55 to +150	°C	
Allowable power dissipation	P _D	600	mW	QFP
		380		LQFP

*¹ AV_{DD} and V_{DD} should be set to a same voltage.

*² V_{IN} and V_{OUT} should not exceed V_{DD} + 0.3V. ($\overline{\text{CS0}}$, $\overline{\text{SI0}}$, PG and PH excluded.)

*³ The large current operation transistors are the N-CH transistors of the PD and PH ports.

Note) Usage exceeding absolute maximum ratings may permanently impair the LSI. Normal operation should better take place under the recommended operating conditions. Exceeding those conditions may adversely affect the reliability of the LSI.

Recommended Operating Conditions

(V_{SS} = 0V)

Item	Symbol	Min.	Max.	Unit	Remarks
Power supply voltage	V _{DD}	3.0	5.5	V	Guaranteed range during high speed mode (1/2 dividing clock) operation
		2.7	5.5	V	Guaranteed range during low speed mode (1/16 dividing clock) operation
		2.5	5.5	V	Guaranteed data hold operation range during STOP
Analog power supply	AV _{DD}	3.0	5.5	V	*1
High level input voltage	V _{IH}	0.7V _{DD}	V _{DD}	V	*2
	V _{IHS}	0.8V _{DD}	V _{DD}	V	CMOS schmitt input*3 and PE0/ $\overline{\text{INT0}}$ pins
			5.5	V	CMOS schmitt input*4
	V _{IHTS}	2.2	5.5	V	TTL schmitt input*5, *8
	V _{IHEX}	V _{DD} - 0.4	V _{DD} + 0.3	V	EXTAL pin*6, *8
		V _{DD} - 0.2	V _{DD} + 0.2	V	EXTAL pin*6, *7
Low level input voltage	V _{IL}	0	0.3V _{DD}	V	*2, *8
			0.2V _{DD}	V	*2, *7
	V _{ILS}	0	0.2V _{DD}	V	CMOS schmitt input*3, *4 and PE0/ $\overline{\text{INT0}}$ pins
	V _{ILTS}	0	0.8	V	TTL schmitt input*5, *8
	V _{ILEX}	-0.3	0.4	V	EXTAL pin*6, *8
		-0.3	0.2	V	EXTAL pin*6, *7
Operating temperature	Topr	-20	+75	°C	

*1 AV_{DD} and V_{DD} should be set to a same voltage.

*2 Normal input port (each pin of PC, PD, PF0 to PF3, PI PJ, and PK), MP pin.

*3 Each pin of SCK0, $\overline{\text{RST}}$, PE1/ $\overline{\text{EC}}$ / $\overline{\text{INT2}}$, PI1/ $\overline{\text{PO}}$, PI4/ $\overline{\text{INT1}}$, PI5/ $\overline{\text{SCK1}}$ and PI7/ $\overline{\text{SI1}}$.

*4 Each pin of $\overline{\text{CS0}}$, SI0, and PG (for PG and PG5, when CMOS schmitt input is selected.)

*5 Each pin of PG4 and PG5 (When TTL schmitt input is selected with mask option)

*6 It specifies only when the external clock is input.

*7 In case of 3.0 to 3.6V supply voltage (V_{DD}).

*8 In case of 4.5 to 5.5V supply voltage (V_{DD}).

Electrical Characteristics

DC Characteristics

Supply voltage (V_{DD}) 4.5 to 5.5V($T_a = -20$ to $+75^\circ\text{C}$, $V_{SS} = 0\text{V}$)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
High level output voltage	V _{OH}	PA to PE, PF4 to PF7, PH (V _{OL} only)	V _{DD} = 4.5V, I _{OH} = −0.5mA	4.0			V
			V _{DD} = 4.5V, I _{OH} = −1.2mA	3.5			V
Low level output voltage	V _{OL}	PI1 to PI7, PJ, SO, SCK, RST*1 (V _{OL} only)	V _{DD} = 4.5V, I _{OL} = 1.8mA			0.4	V
			V _{DD} = 4.5V, I _{OL} = 3.6mA			0.6	V
		PD, PH	V _{DD} = 4.5V, I _{OL} = 12.0mA			1.5	V
Input current	I _{IHE}	EXTAL	V _{DD} = 5.5V, V _{IH} = 5.5V	0.5		40	μA
	I _{ILE}		V _{DD} = 5.5V, V _{IL} = 0.4V	−0.5		−40	μA
	I _{ILR}	RST*2	V _{DD} = 5.5V, V _{IL} = 0.4V	−1.5		−400	μA
I/O leakage current	I _{IZ}	PA to PK, MP, AN0 to AN3, CS, SI, SO, SCK, RST*2	V _{DD} =5.5V, V _I = 0, 5.5V			±10	μA
Supply current*3	I _{DD1}	V _{DD}	Crystal oscillation (C ₁ = C ₂ = 15pF) of 16MHz		31	50	mA
			V _{DD} = 5V ± 0.5V*4				
	I _{DDS1}		SLEEP mode		2.0	8.0	mA
			V _{DD} = 5V ± 0.5V				
			I _{DDS3}	STOP mode			
V _{DD} = 5.5V							
Input capacity	C _{IN}	Other than V _{DD} , V _{SS} , AV _{DD} , and AV _{SS} pins	Clock 1MHz 0V other than the measured pins		10	20	pF

^{*1} $\overline{\text{RST}}$ pin specifies only when the power on reset circuit has been selected with mask option.

^{*2} $\overline{\text{RST}}$ pin specifies the input current when the pull-up resistor is selected, and specifies leakage current when non-resistance is selected.

^{*3} When entire output pins are open.

^{*4} When setting upper 2 bits (CPU clock selection) of clock control register CLC (address: 00FE_H) to "00" and operating in high speed mode (1/2 dividing clock).

Supply voltage (V_{DD}) 3.0 to 3.6V($T_a = -20$ to $+75^\circ\text{C}$, $V_{SS} = 0\text{V}$)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
High level output voltage	V _{OH}	PA to PE, PF4 to PF7, PH (V _{OL} only)	V _{DD} = 3.0V, I _{OH} = −0.15mA	2.7			V
			V _{DD} = 3.0V, I _{OH} = −0.5mA	2.3			V
Low level output voltage	V _{OL}	PI1 to PI7, PJ, SO, SCK, RST*1 (V _{OL} only)	V _{DD} = 3.0V, I _{OL} = 1.2mA			0.3	V
			V _{DD} = 3.0V, I _{OL} = 1.6mA			0.5	V
		PD, PH	V _{DD} = 3.0V, I _{OL} = 5.0mA			1.0	V
Input current	I _{IHE}	EXTAL	V _{DD} = 3.6V, V _{IH} = 3.6V	0.3		20	μA
	I _{ILE}		V _{DD} = 3.6V, V _{IL} = 0.3V	−0.3		−20	μA
	I _{ILR}	RST*2	V _{DD} = 3.6V, V _{IL} =0.3V	−0.9		−200	μA
I/O leakage current	I _{IZ}	PA to PK, MP, AN0 to AN3, CS, SI, SO, SCK, RST*2	V _{DD} = 5.5V, V _I = 0, 5.5V			±10	μA
Supply current*3	I _{DD2}	V _{DD}	Crystal oscillation (C ₁ = C ₂ = 15pF) of 12MHz		15	30	mA
			V _{DD} = 3.3V ± 0.3V*4				
	I _{DDS2}		SLEEP mode		0.8	2.5	mA
			V _{DD} = 3.3V ± 0.3V				
	I _{DDS3}		STOP mode				10
V _{DD} = 5.5V							
Input capacity	C _{IN}	Other than V _{DD} , V _{SS} , AV _{DD} , and AV _{SS} pins	Clock 1MHz 0V other than the measured pins		10	20	pF

*1 $\overline{\text{RST}}$ pin specifies only where the power on reset circuit has been selected with mask option.

*2 $\overline{\text{RST}}$ pin specifies the input current when the pull-up resistor is selected, and specifies leakage current when non-resistance is selected.

*3 When entire output pins are open.

*4 When setting upper 2 bits (CPU clock selection) of clock control register CLC (address: 00FEH) to "00" and operating in high speed mode (1/2 dividing clock).

AC Characteristics

(1) Clock timing

(Ta = -20 to +75°C, V_{DD} = 3.0 to 5.5V, V_{SS} = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
System clock frequency	f _c	XTAL EXTAL	Fig. 1, Fig. 2 V _{DD} = 4.5 to 5.5V	1	16	MHz
				1	12	
System clock input pulse width	t _{XL} , t _{xH}	XTAL EXTAL	Fig. 1, Fig. 2 (External clock drive) V _{DD} = 4.5 to 5.5V	28		ns
				37.5		
System clock input rising and falling times	t _{CR} , t _{CF}	XTAL EXTAL	Fig. 1, Fig. 2 (External clock drive)		200	ns
Event count clock input pulse width	t _{EL} , t _{EH}	PE1/ $\overline{\text{EC}}$	Fig. 3	t _{sys} × 4*		ns
Event count clock input rising and falling times	t _{ER} , t _{EF}	PE1/ $\overline{\text{EC}}$	Fig. 3		20	ms

* t_{sys} indicates three values according to the contents of the clock control register (address; 00FE_H) upper 2 bits (CPU clock selection).

t_{sys} [ns] = 2000/f_c (Upper 2 bits = "00"), 4000/f_c (Upper 2 bits = "01"), 16000/f_c (Upper 2 bits = "11")

Fig. 1. Clock timing

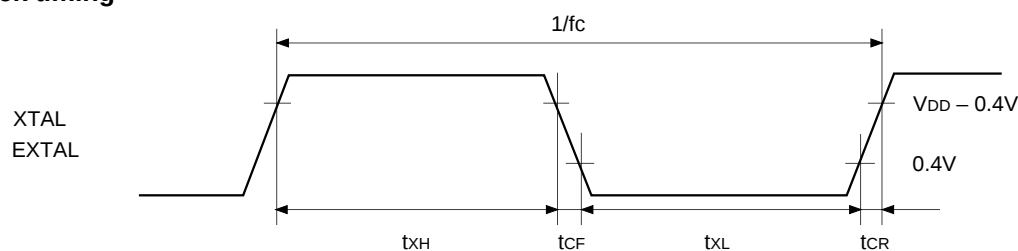


Fig. 2. Clock applied condition

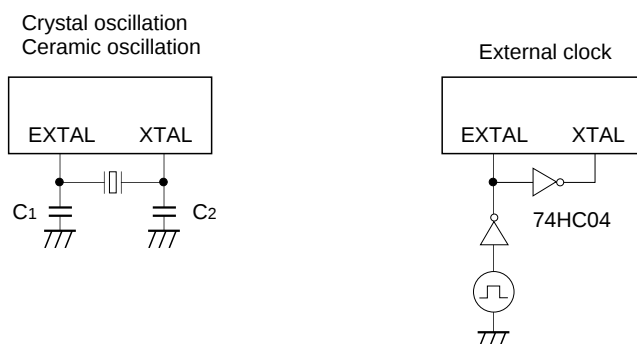
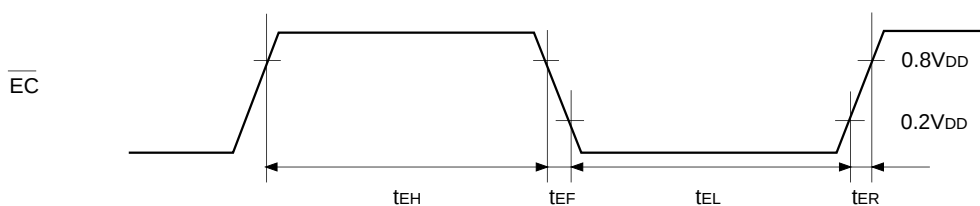


Fig. 3. Event count clock timing



(2) Serial transfer (CH0)

(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
$\overline{\text{CS}} \downarrow \rightarrow \overline{\text{SCK}}$ delay time	t_{DCSK}	$\overline{\text{SCK0}}$	Chip select transfer mode ($\overline{\text{SCK}}$ = output mode)		$t_{\text{sys}} + 200$	ns
$\overline{\text{CS}} \uparrow \rightarrow \overline{\text{SCK}}$ floating delay time	t_{DCSKF}	$\overline{\text{SCK0}}$	Chip select transfer mode ($\overline{\text{SCK}}$ = output mode)		$t_{\text{sys}} + 200$	ns
$\overline{\text{CS}} \downarrow \rightarrow \text{SO}$ delay time	t_{DCSO}	SO0	Chip select transfer mode		$t_{\text{sys}} + 200$	ns
$\overline{\text{CS}} \downarrow \rightarrow \text{SO}$ floating delay time	t_{DCSOF}	SO0	Chip select transfer mode		$t_{\text{sys}} + 200$	ns
$\overline{\text{CS}}$ high level width	t_{WHCS}	$\overline{\text{CS0}}$	Chip select transfer mode	$t_{\text{sys}} + 200$		ns
$\overline{\text{SCK}}$ cycle time	t_{KCY}	$\overline{\text{SCK0}}$	Input mode	$2t_{\text{sys}} + 200$		ns
			Output mode	$8000/f_c$		ns
$\overline{\text{SCK}}$ high and low level widths	t_{KH} t_{KL}	$\overline{\text{SCK0}}$	Input mode	$t_{\text{sys}} + 100$		ns
			Output mode	$8000/f_c - 100$		ns
SI input setup time (against $\overline{\text{SCK}} \uparrow$)	t_{SIK}	SI0	$\overline{\text{SCK}}$ input mode	$-t_{\text{sys}} + 100$		ns
			$\overline{\text{SCK}}$ output mode	200		ns
SI input hold time (against $\overline{\text{SCK}} \uparrow$)	t_{KSI}	SI0	$\overline{\text{SCK}}$ input mode	$2t_{\text{sys}} + 100$		ns
			$\overline{\text{SCK}}$ output mode	100		ns
$\overline{\text{SCK}} \downarrow \rightarrow \text{SO}$ delay time	t_{KSO}	SO0	$\overline{\text{SCK}}$ input mode		$2t_{\text{sys}} + 200$	ns
			$\overline{\text{SCK}}$ output mode		100	ns

Note 1) t_{sys} indicates three values according to the contents of the clock control register (address; 00FEH) upper 2 bits (CPU clock selection).

t_{sys} [ns] = 2000/ f_c (Upper 2 bits = "00"), 4000/ f_c (Upper 2 bits = "01"), 16000/ f_c (Upper 2 bits = "11")

Note 2) $\overline{\text{CS}}$, $\overline{\text{SCK}}$, SI and SO means each pin of $\overline{\text{CS}} \rightarrow \overline{\text{CS0}}$, $\overline{\text{SCK}} \rightarrow \overline{\text{SCK0}}$, SI $\rightarrow$ SI0, and SO $\rightarrow$ SO0 respectively.

Note 3) The load of $\overline{\text{SCK}}$ output mode and SO output delay time is 50pF + 1TTL.

Serial transfer (CH0)

(Ta = -20 to +75°C, V_{DD} = 3.0 to 3.6V, V_{SS} = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
$\overline{CS} \downarrow \rightarrow \overline{SCK}$ delay time	t _{DCSK}	$\overline{SCK0}$	Chip select transfer mode ($\overline{SCK}$ = output mode)		t _{sys} + 250	ns
$\overline{CS} \uparrow \rightarrow \overline{SCK}$ floating delay time	t _{DCSKF}	$\overline{SCK0}$	Chip select transfer mode ($\overline{SCK}$ = output mode)		t _{sys} + 200	ns
$\overline{CS} \downarrow \rightarrow SO$ delay time	t _{DCSO}	SO0	Chip select transfer mode		t _{sys} + 250	ns
$\overline{CS} \downarrow \rightarrow SO$ floating delay time	t _{DCSOF}	SO0	Chip select transfer mode		t _{sys} + 200	ns
$\overline{CS}$ high level width	t _{WHCS}	$\overline{CS0}$	Chip select transfer mode	t _{sys} + 200		ns
$\overline{SCK}$ cycle time	t _{KCY}	$\overline{SCK0}$	Input mode	2t _{sys} + 200		ns
			Output mode	16000/fc		ns
$\overline{SCK}$ high and low level widths	t _{KH} t _{KL}	$\overline{SCK0}$	Input mode	t _{sys} + 100		ns
			Output mode	8000/fc - 150		ns
SI input setup time (against $\overline{SCK} \uparrow$)	t _{SIK}	SI0	$\overline{SCK}$ input mode	-t _{sys} + 100		ns
			$\overline{SCK}$ output mode	200		ns
SI input hold time (against $\overline{SCK} \uparrow$)	t _{KSI}	SI0	$\overline{SCK}$ input mode	2t _{sys} + 100		ns
			$\overline{SCK}$ output mode	100		ns
$\overline{SCK} \downarrow \rightarrow SO$ delay time	t _{KSO}	SO0	$\overline{SCK}$ input mode		2t _{sys} + 250	ns
			$\overline{SCK}$ output mode		125	ns

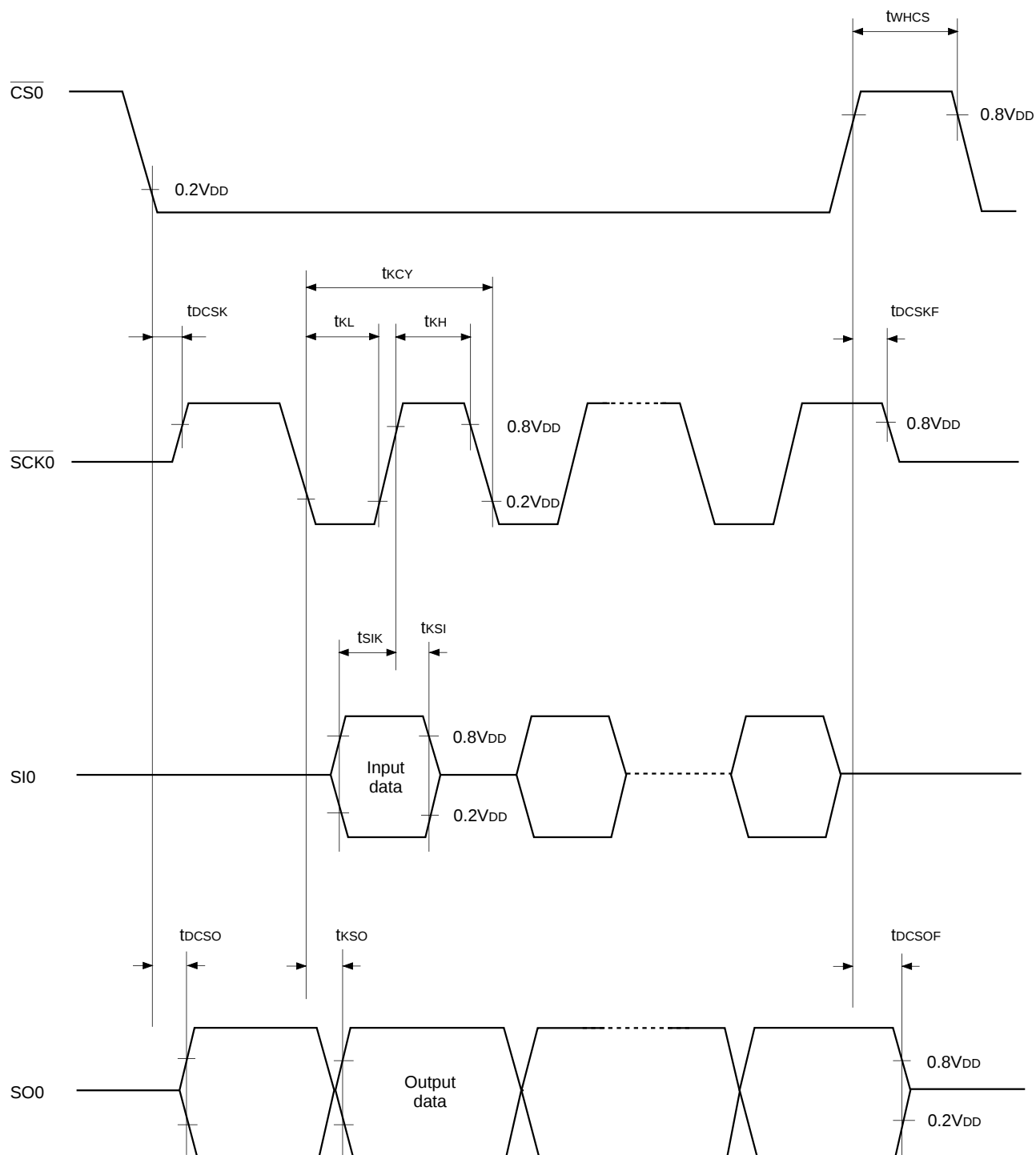
Note 1) t_{sys} indicates three values according to the contents of the clock control register (address; 00FEH) upper 2 bits (CPU clock selection).

t_{sys} [ns] = 2000/fc (Upper 2 bits = "00"), 4000/fc (Upper 2 bits = "01"), 16000/fc (Upper 2 bits = "11")

Note 2) $\overline{CS}$, $\overline{SCK}$, SI and SO means each pin of $\overline{CS} \rightarrow \overline{CS0}$, $\overline{SCK} \rightarrow \overline{SCK0}$, SI $\rightarrow$ SI0, and SO $\rightarrow$ SO0 respectively.

Note 3) The load of $\overline{SCK}$ output mode and SO output delay time is 50pF.

Fig. 4. Serial transfer timing (CH0)



Serial transfer (CH1) (SIO mode)

(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
$\overline{\text{SCK1}}$ cycle time	t_{KCY}	$\overline{\text{SCK1}}$	Input mode	$2t_{\text{sys}} + 200$		ns
			Output mode	$16000/f_c$		ns
$\overline{\text{SCK1}}$ high and low level widths	t_{KH} t_{KL}	$\overline{\text{SCK1}}$	Input mode	$t_{\text{sys}} + 100$		ns
			Output mode	$8000/f_c - 100$		ns
SI1 input setup time (against $\overline{\text{SCK1}}$ ↑)	t_{SIK}	SI1	$\overline{\text{SCK1}}$ input mode	100		ns
			$\overline{\text{SCK1}}$ output mode	200		ns
SI1 input hold time (against $\overline{\text{SCK1}}$ ↑)	t_{KSI}	SI1	$\overline{\text{SCK1}}$ input mode	$t_{\text{sys}} + 200$		ns
			$\overline{\text{SCK1}}$ output mode	100		ns
$\text{SCK1} \downarrow \rightarrow \text{SO1}$ delay time	t_{KSO}	SO1	$\overline{\text{SCK1}}$ input mode		$t_{\text{sys}} + 200$	ns
			$\overline{\text{SCK1}}$ output mode		100	ns

Note 1) t_{sys} indicates three values according to the contents of the clock control register (address; 00FE_H) upper 2 bits (CPU clock selection).

t_{sys} [ns] = 2000/ f_c (Upper 2 bits = "00"), 4000/ f_c (Upper 2 bits = "01"), 16000/ f_c (Upper 2 bits = "11")

Note 2) The load of $\overline{\text{SCK1}}$ output mode and SO1 output delay time is 50pF + 1TTL.

Serial transfer (CH1) (SIO mode)

(Ta = -20 to +75°C, V_{DD} = 3.0 to 3.6V, V_{SS} = 0V)

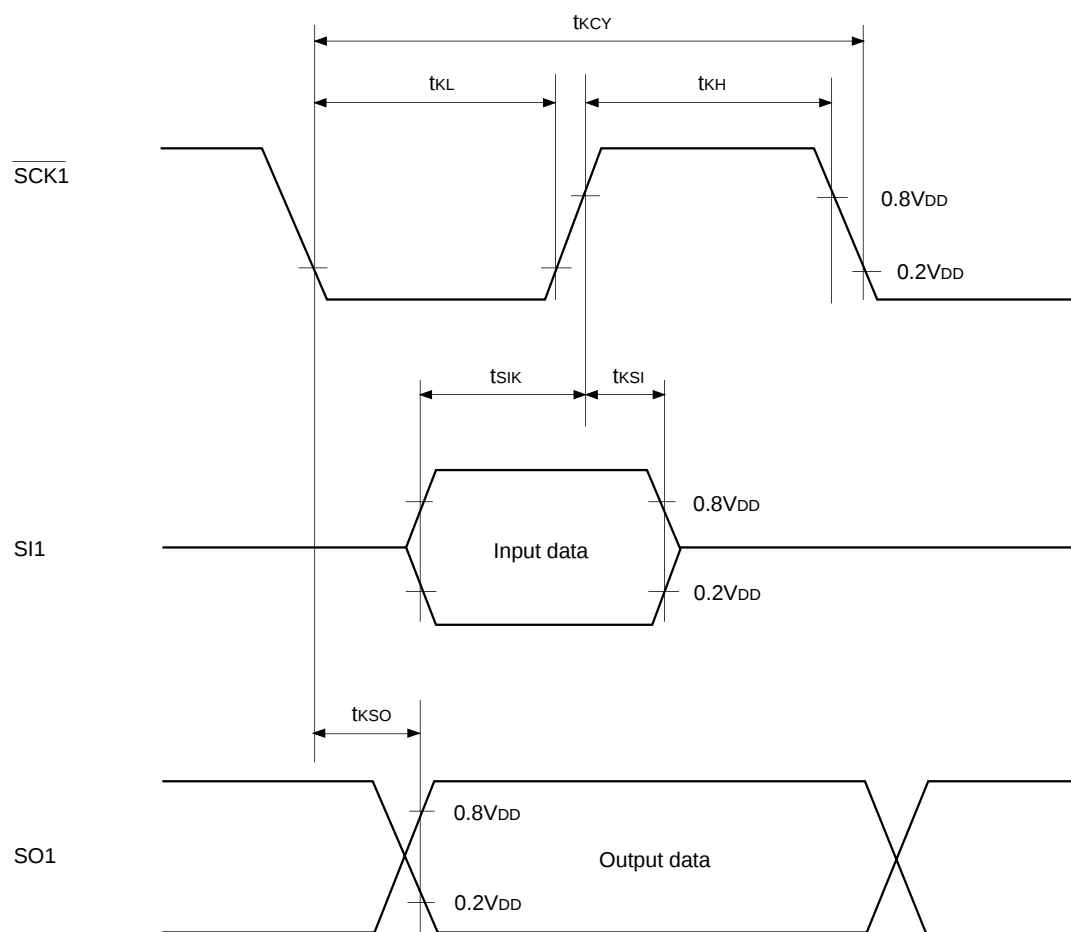
Item	Symbol	Pin	Condition	Min.	Max.	Unit
$\overline{\text{SCK1}}$ cycle time	t_{KCY}	$\overline{\text{SCK1}}$	Input mode	$2t_{\text{sys}} + 200$		ns
			Output mode	$16000/f_c$		ns
$\overline{\text{SCK1}}$ high and low level widths	t_{KH} t_{KL}	$\overline{\text{SCK1}}$	Input mode	$t_{\text{sys}} + 100$		ns
			Output mode	$8000/f_c - 150$		ns
SI1 input setup time (against $\overline{\text{SCK1}}$ ↑)	t_{SIK}	SI1	$\overline{\text{SCK1}}$ input mode	100		ns
			$\overline{\text{SCK1}}$ output mode	200		ns
SI1 input hold time (against $\overline{\text{SCK1}}$ ↑)	t_{KSI}	SI1	$\overline{\text{SCK1}}$ input mode	$t_{\text{sys}} + 200$		ns
			$\overline{\text{SCK1}}$ output mode	100		ns
$\text{SCK1} \downarrow \rightarrow \text{SO1}$ delay time	t_{KSO}	SO1	$\overline{\text{SCK1}}$ input mode		$t_{\text{sys}} + 250$	ns
			$\overline{\text{SCK1}}$ output mode		125	ns

Note 1) t_{sys} indicates three values according to the contents of the clock control register (address; 00FE_H) upper 2 bits (CPU clock selection).

t_{sys} [ns] = 2000/ f_c (Upper 2 bits = "00"), 4000/ f_c (Upper 2 bits = "01"), 16000/ f_c (Upper 2 bits = "11")

Note 2) The load of $\overline{\text{SCK1}}$ output mode and SO1 output delay time is 50pF.

Fig. 5. Serial transfer CH1 timing (SIO mode)



Serial transfer (CH1) (Special mode)(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
SO1 cycle time	t _{LCY}	SO1 SI1	Note 1)		104		μs
SI1 data setup time	t _{LSU}	SI1		2			μs
SI1 data hold time	t _{LHD}	SI1		2			μs

Note 1) t_{LCY} specifies only serial mode register (CH1) (SIOM1: Address 01FA_H) lower 2 bits (SO1 clock selection) has been set at 104μs.

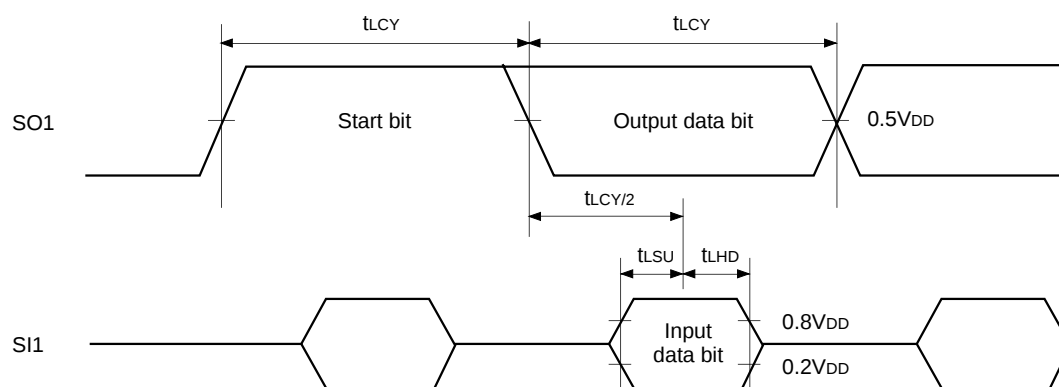
Note 2) The load of SO1 pin is 50pF + 1TTL.

Serial transfer (CH1) (Special mode)(Ta = -20 to +75°C, V_{DD} = 3.0 to 3.6V, V_{SS} = 0V)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
SO1 cycle time	t _{LCY}	SO1 SI1	Note 1)		104		μs
SI1 data setup time	t _{LSU}	SI1		2			μs
SI1 data hold time	t _{LHD}	SI1		2			μs

Note 1) t_{LCY} specifies only serial mode register (CH1) (SIOM1: Address 01FA_H) lower 2 bits (SO1 clock selection) has been set at 104μs.

Note 2) The load of SO1 pin is 50pF.

Fig. 6. Serial transfer CH1 timing (Special mode)

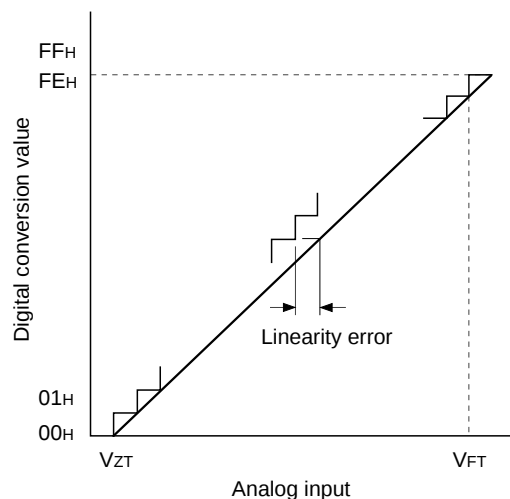
(3) A/D converter characteristics ($T_a = -20$ to $+75^\circ\text{C}$, $V_{DD} = AV_{DD} = 4.5$ to 5.5V , $AV_{REF} = 4.0$ to AV_{DD} , $V_{SS} = AV_{SS} = 0\text{V}$)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
Resolution						8	Bits
Linearity error			Only for A/D converter operation $T_a = 25^\circ\text{C}$ $V_{DD} = AV_{DD} = AV_{REF} = 5.0\text{V}$ $V_{SS} = AV_{SS} = 0\text{V}$			± 1	LSB
Absolute error						± 2	LSB
Conversion time	t_{CONV}			$160/f_{\text{ADC}}$			μs
Sampling time	t_{SAMP}			$12/f_{\text{ADC}}$			μs
Reference input voltage	V_{REF}	AV_{REF}	$V_{DD} = AV_{DD} = 4.5$ to 5.5V	$AV_{DD} - 0.5$		AV_{DD}	V
Analog input voltage	V_{IAN}	AN0 to AN11		0		AV_{REF}	V
AV_{REF} current	I_{REF}	AV_{REF}	Operating mode $AV_{\text{REF}} = 4.0$ to 5.5V		0.6	1.0	mA
			SLEEP mode STOP mode			10	μA

A/D converter characteristics ($T_a = -20$ to $+75^\circ\text{C}$, $V_{DD} = AV_{DD} = 3.0$ to 3.6V , $AV_{REF} = 2.7$ to AV_{DD} , $V_{SS} = AV_{SS} = 0\text{V}$)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
Resolution						8	Bits
Linearity error			Only for A/D converter operation $T_a = 25^\circ\text{C}$ $V_{DD} = AV_{DD} = AV_{REF} = 3.3\text{V}$ $V_{SS} = AV_{SS} = 0\text{V}$			± 1	LSB
Absolute error						± 2	LSB
Conversion time	t_{CONV}			$160/f_{\text{ADC}}$			μs
Sampling time	t_{SAMP}			$12/f_{\text{ADC}}$			μs
Reference input voltage	V_{REF}	AV_{REF}	$V_{DD} = AV_{DD} = 3.0$ to 3.6V	$AV_{DD} - 0.3$		AV_{DD}	V
Analog input voltage	V_{IAN}	AN0 to AN11		0		AV_{REF}	V
AV_{REF} current	I_{REF}	AV_{REF}	Operating mode $AV_{\text{REF}} = 2.7$ to 3.6V		0.4	0.7	mA
			SLEEP mode STOP mode			10	μA

Fig. 7. Definitions of A/D converter terms



* The value of f_{ADC} is as follows by selecting ADC operation clock (MSC: Address 01FFH bit 0).

When PS2 is selected, $f_{\text{ADC}} = f_c/2$

When PS1 is selected, $f_{\text{ADC}} = f_c$

(4) Interruption, reset input (Ta = -20 to +75°C, VDD = 3.0 to 5.5V, VSS = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
External interruption high and low level widths	t _{IH} t _{IL}	$\overline{\text{INT0}}$ $\overline{\text{INT1}}$ $\overline{\text{INT2}}$ PJ0 to PJ7		1		μs
Reset input low level width	t _{RSL}	$\overline{\text{RST}}$		32/fc		μs

Fig. 8. Interruption input timing

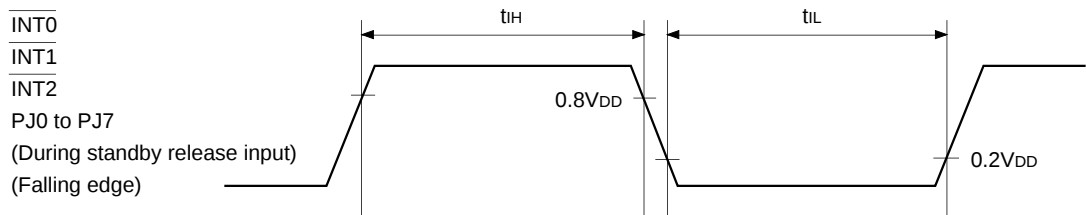
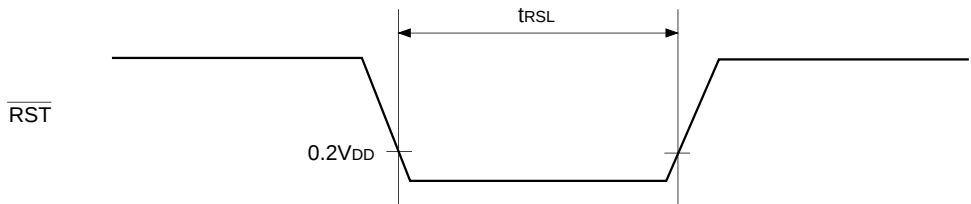


Fig. 9. Reset input timing



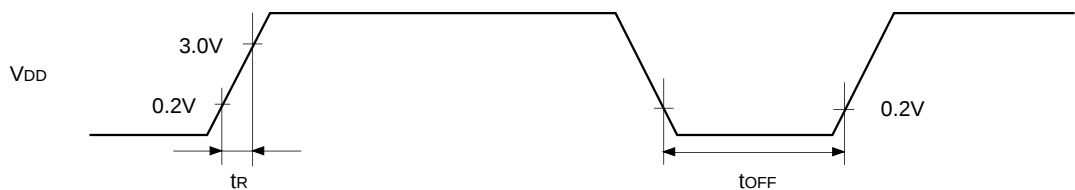
(5) Power on reset

Power on reset* (Ta = -20 to +75°C, VDD = 3.0 to 5.5V, VSS = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
Power supply rising edge	t _R	V _{DD}	Power on reset	0.05	30	ms
Power supply cut-off time	t _{OFF}		Repetitive power on reset	1		ms

* Specifies only when power on reset function is selected.

Fig. 10. Power on reset



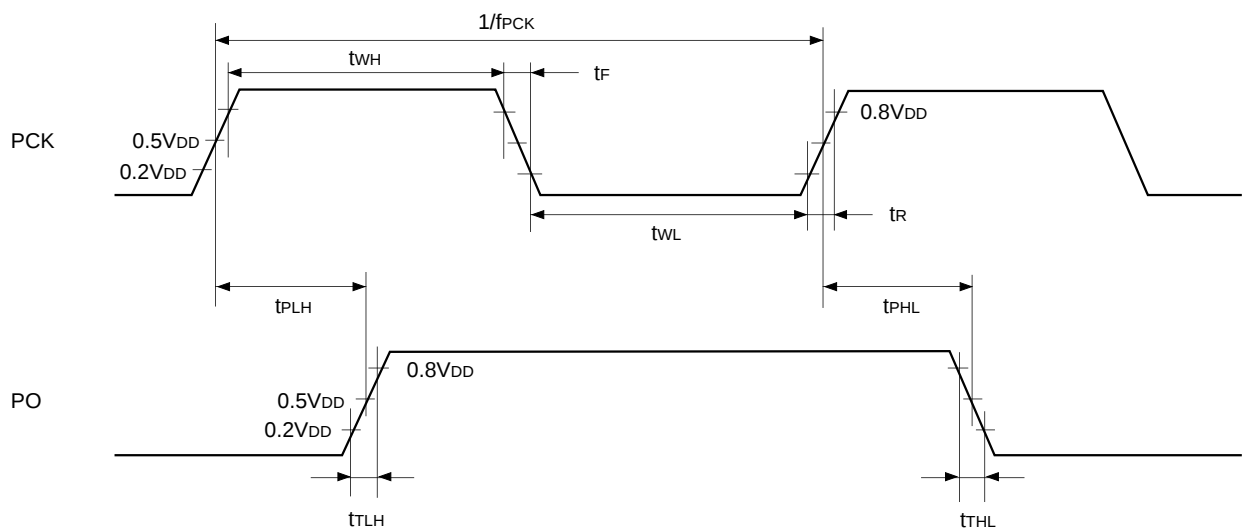
The power supply should rise smoothly.

(6) General purpose prescaler(Ta = -20 to +75°C, V_{DD} = 4.5 to 5.5V, V_{SS} = 0V)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
External clock input frequency	f _{PCK}	PCK				12	MHz
External clock input pulse width	t _{WH} , t _{WL}	PCK		33			ns
External clock input rising and falling times	t _R , t _F	PCK				200	ns
Prescaler output delay time (against PCK ↑)	t _{PLH}	PO	External clock input PCK t _R = t _F = 6ns		80	130	ns
	t _{PHL}				60	100	ns
Prescaler output rising and falling times	t _{TLH}	PO	External clock input PCK t _R = t _F = 6ns		50	100	ns
	t _{THL}				20	40	ns

Note) The load of PO pin is 50pF.**General purpose prescaler**(Ta = -20 to +75°C, V_{DD} = 3.0 to 3.6V, V_{SS} = 0V)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
External clock input frequency	f _{PCK}	PCK				12	MHz
External clock input pulse width	t _{WH} , t _{WL}	PCK		33			ns
External clock input rising and falling times	t _R , t _F	PCK				200	ns
Prescaler output delay time (against PCK ↑)	t _{PLH}	PO	External clock input PCK t _R = t _F = 6ns		130	220	ns
	t _{PHL}				90	150	ns
Prescaler output rising and falling times	t _{TLH}	PO	External clock input PCK t _R = t _F = 6ns		100	280	ns
	t _{THL}				30	70	ns

Note) The load of PO pin is 50pF.**Fig. 11. General purpose prescaler timing**

(7) Others

(Ta = -20 to +75°C, V_{DD} = 3.0 to 5.5V, V_{SS} = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
CFG input high and low level widths	t _{CFH} t _{CFL}	CFG		t _{FRC} × 24 + 200		ns
DFG input high and low level widths	t _{DFH} t _{DFL}	DFG		t _{FRC} × 8 + 200		ns
DPG minimum pulse width	t _{DPW}	DPG		50		ns
DPG minimum removal time	t _{trem}	DPG		50		ns
PBCTL input high and low level widths	t _{CTH} t _{CTL}	PBCTL	t _{sys} = 2000/fc	t _{FRC} × 8 + t _{sys} + 200		ns
EXI input high and low level widths	t _{EIH} t _{EIL}	EXI0 EXI1	t _{sys} = 2000/fc	t _{FRC} × 8 + t _{sys} + 200		ns
PMI input high and low level widths	t _{PIH} t _{PIL}	PMI		t _{sys} + 200		ns
PMSK input high and low level widths	t _{PSH} t _{PSL}	PMSK		t _{sys} + 200		ns

Note 1) t_{sys} indicates three values according to the contents of the clock control register (address; 00FE_H) upper 2 bits (CPU clock selection).

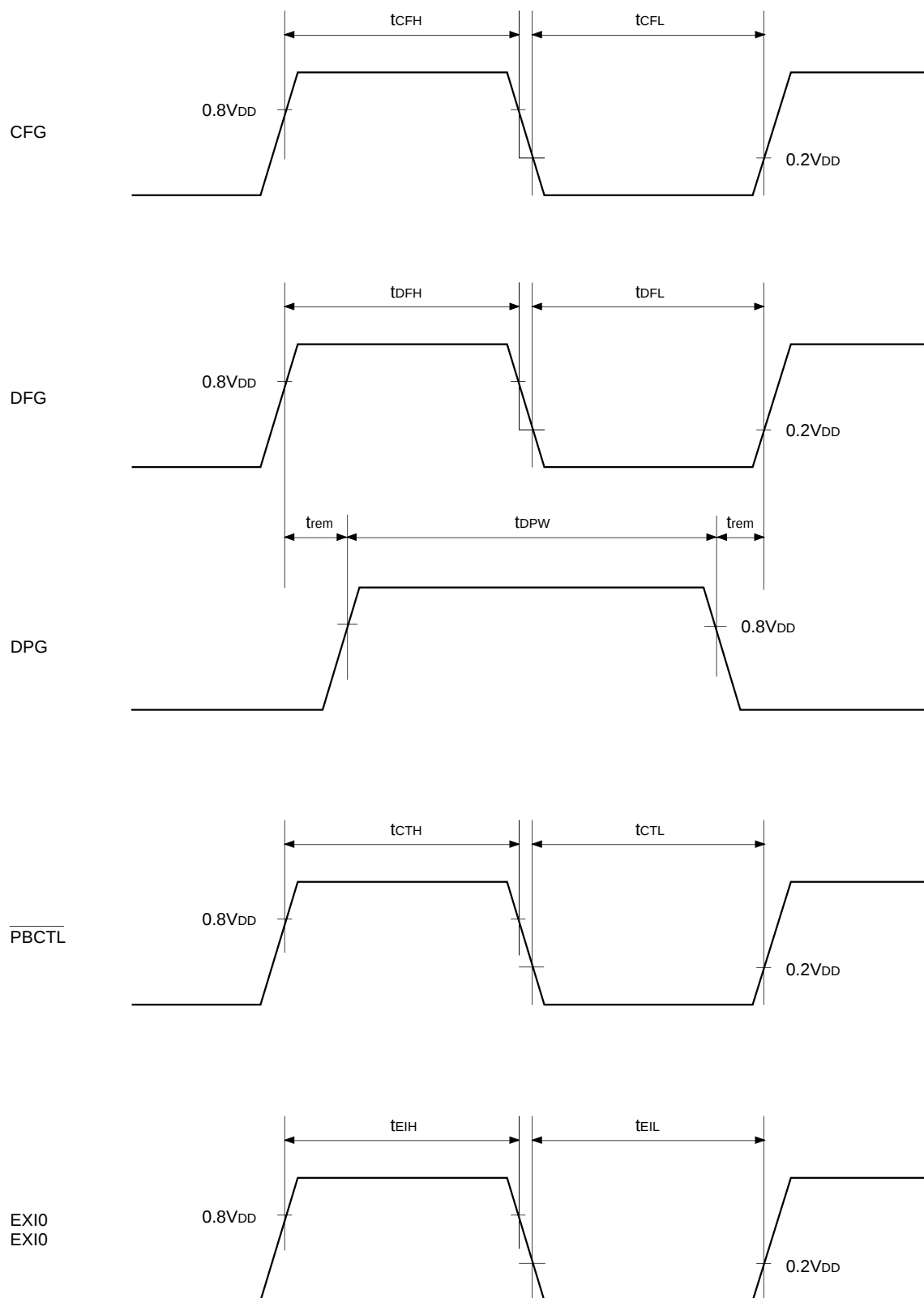
t_{sys} [ns] = 2000/fc (Upper 2 bits = "00"), 4000/fc (Upper 2 bits = "01"), 16000/fc (Upper 2 bits = "11")

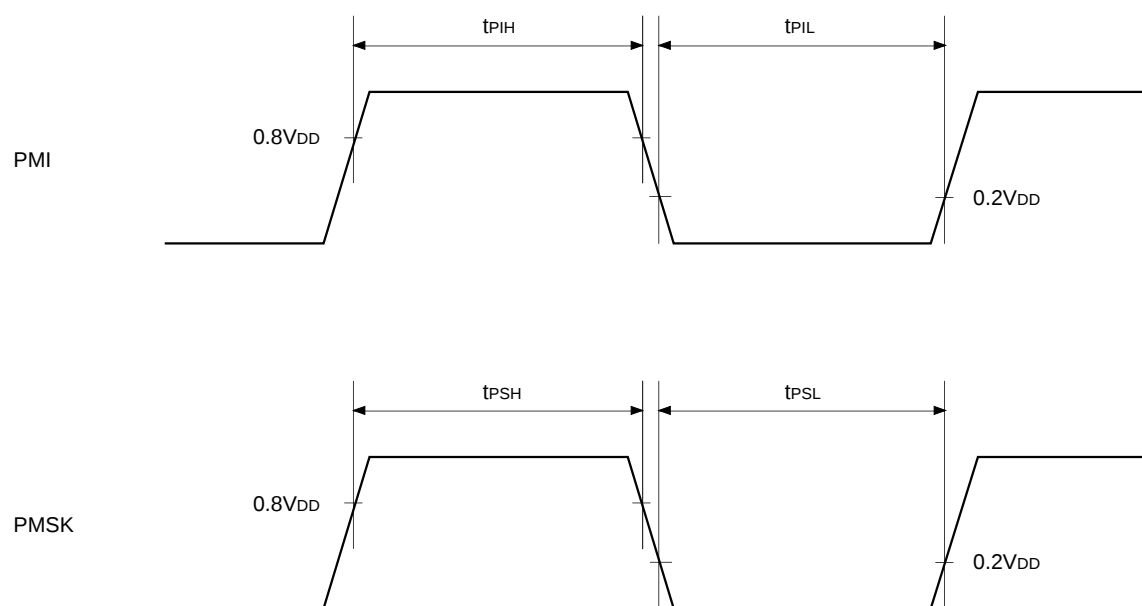
Note 2) The value of t_{FRC} is as follows by selecting FRC clock (FRCS: 01EE_H bit 7)

When PS0 is selected, t_{FRC} = 1000/fc (ns)

When PS1 is selected, t_{FRC} = 2000/fc (ns)

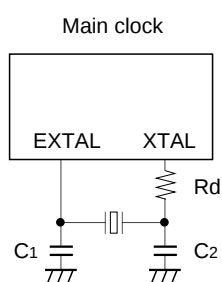
Fig. 12. Other timings





Supplement

Fig. 13. Recommended oscillation circuit



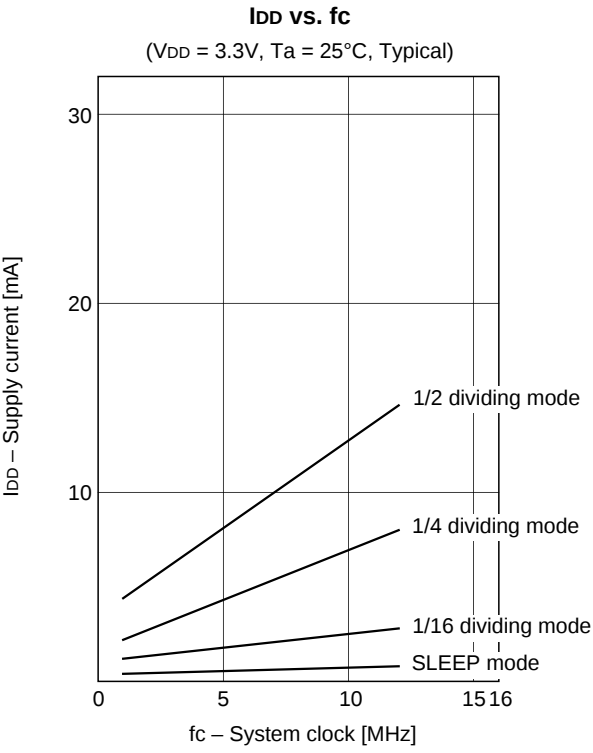
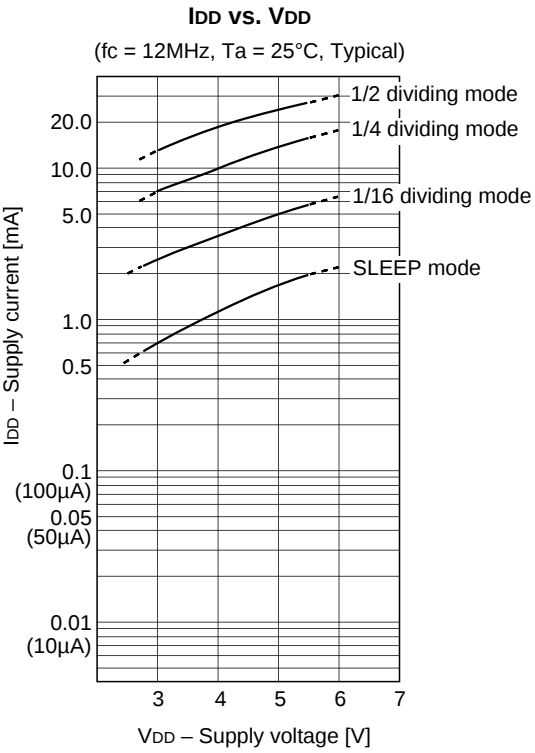
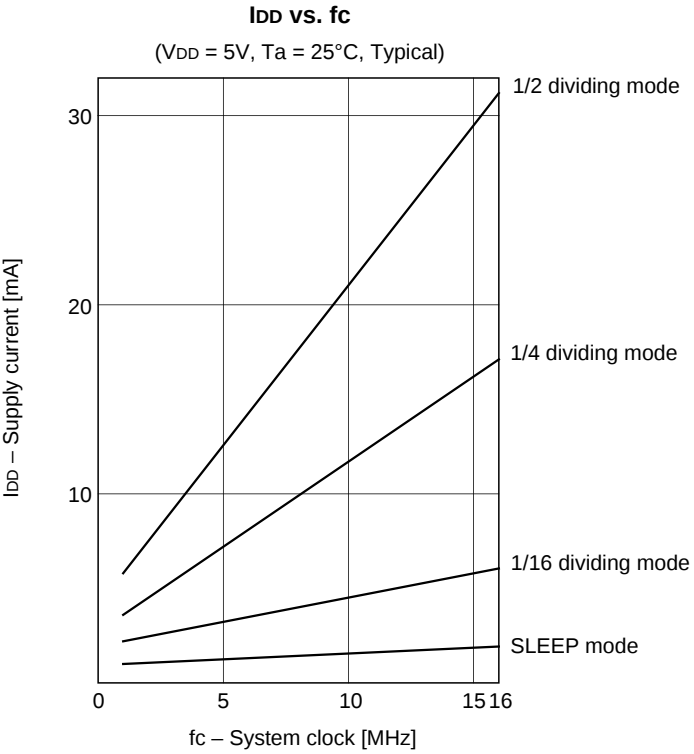
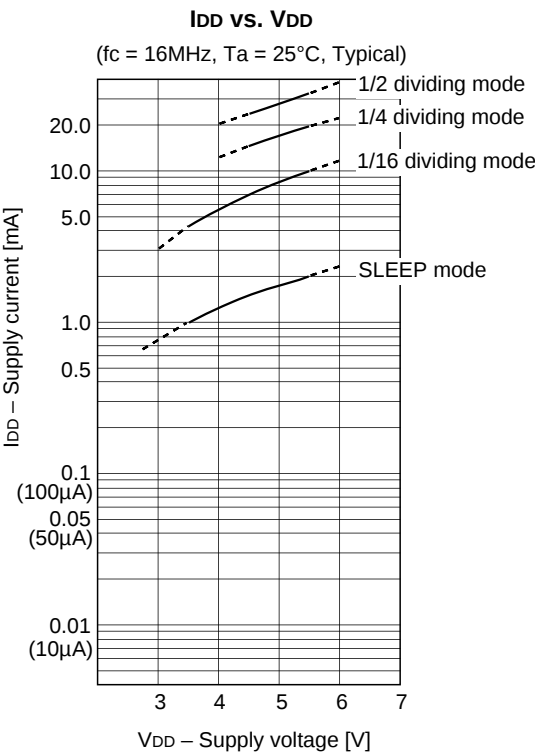
Manufacturer	Model	fc (MHz)	C ₁ (pF)	C ₂ (pF)	R _d (Ω)	Circuit example
RIVER ELETEC CO., LTD.	HC-49/U03	8.00	10	10	0	(i)
		10.00				
		12.00				
		16.00				
KINSEKI LTD.	HC-49/U (-S)	8.00	22 (15)	22 (15)	0	(i)
		10.00				
		12.00	15	15		
		16.00	12	12		

Mask Option Table

Item	Content	
Reset pin pull-up resistor	Non-existent	Existent
Power on reset circuit	Non-existent	Existent
General purpose prescaler oscillation circuit	Non-existent	Existent
Input circuit format*	CMOS schmitt	TTL schmitt

* In PG4/SYNC0/PMI pin and PG5/SYNC1 pin, the input circuit format can be selected every pin. However, TTL schmitt can not be selected when the supply voltage (V_{DD}) ranges from 3.5V to 5.5V.

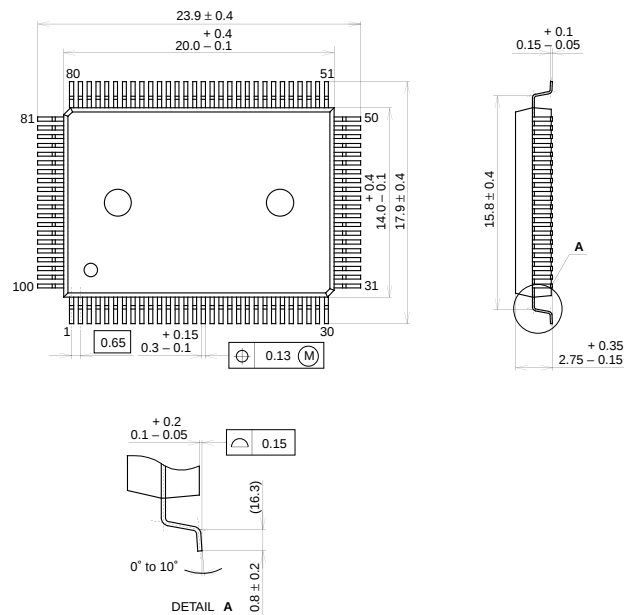
Characteristics Curve



Package Outline

Unit: mm

100PIN QFP (PLASTIC)

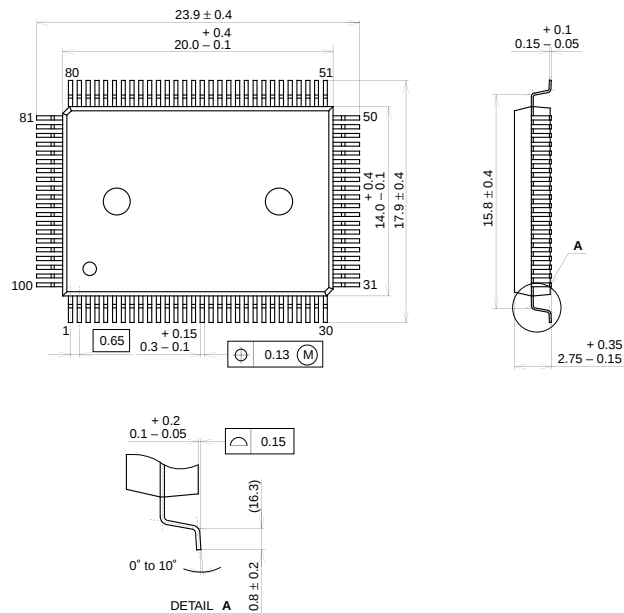


PACKAGE STRUCTURE

SONY CODE	QFP-100P-L01
EIAJ CODE	QFP100-P-1420
JEDEC CODE	

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	1.7g

100PIN QFP (PLASTIC)



PACKAGE STRUCTURE

SONY CODE	QFP-100P-L01
EIAJ CODE	QFP100-P-1420
JEDEC CODE	

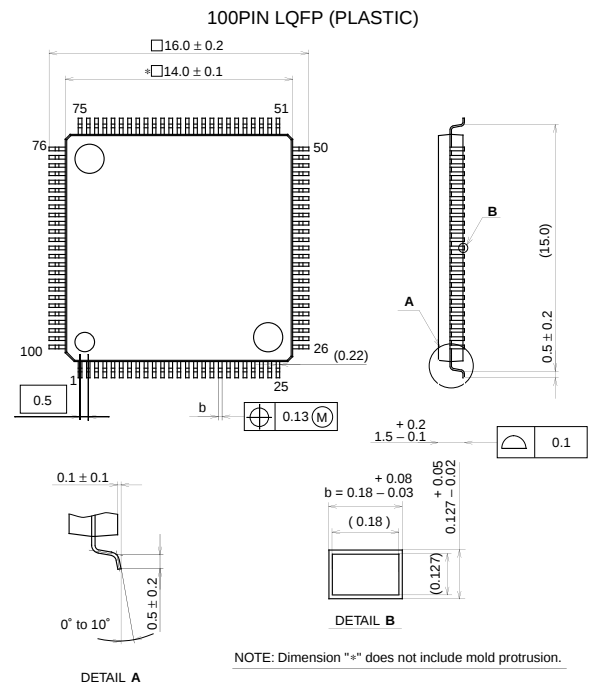
PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	1.7g

LEAD PLATING SPECIFICATIONS

ITEM	SPEC.
LEAD MATERIAL	42 ALLOY
SOLDER COMPOSITION	Sn-Bi Bi:1-4wt%
PLATING THICKNESS	5-18μm

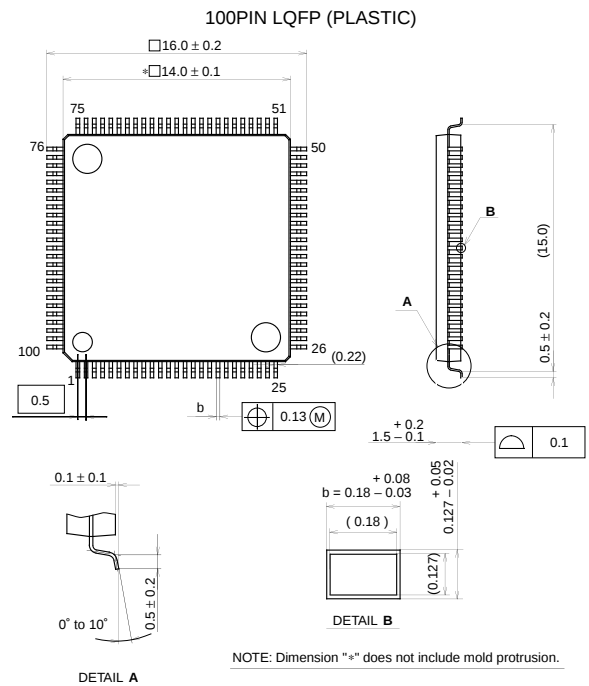
Package Outline

Unit: mm



SONY CODE	LQFP-100P-L01
EIAJ CODE	P-LQFP100-14x14-0.5
JEDEC CODE	

PACKAGE STRUCTURE	
PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42 / COPPER ALLOY
PACKAGE MASS	0.7g



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PACKAGE STRUCTURE	
PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42 / COPPER ALLOY
PACKAGE MASS	0.7g

LEAD PLATING SPECIFICATIONS

ITEM	SPEC.
LEAD MATERIAL	42 ALLOY
SOLDER COMPOSITION	Sn-Bi Bi:1-4wt%
PLATING THICKNESS	5-18 μ m